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L24: Entry 1 of 1

File: DWPI

May 14, 1996

DERWENT-ACC-NO: 1996-281730

DERWENT-WEEK: 199629

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TITLE: Soldering ball mounting device - comprises work positioning part to position work with electrodes upward, template with through-holes corresp to electrodes, etc.

INVENTOR: NISHINAKA, T; SAKEMI, S

PATENT-ASSIGNEE:

ASSIGNEE	CODE
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PRIORITY-DATA:

1994JP-0205106

August 30, 1994

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 08118005 A	May 14, 1996	N/A	006	B23K003/06
US 5655704 A	August 12, 1997	N/A	009	B23K001/20

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-NO
JP08118005A	August 3, 1995	1995JP-0198550	N/A
US 5655704A	August 28, 1995	1995US-0520284	N/A

INT-CL (IPC): B23K 1/20; B23K 3/06; H01L 21/321; H01L 21/60; H05K 3/34

ABSTRACTED-PUB-NO: JP08118005A ✓

BASIC-ABSTRACT:

The device comprises a work positioning part to position a work with electrodes upward, a template with through-holes corresp to the electrodes, respectively, supported for the through-holes to be located on the electrodes, a soldering ball storage and a moving means to horizontally move the storage along the template.

ADVANTAGE - Transfer of soldering balls to BGA electrodes is ensured.
ABSTRACTED-PUB-NO:

US 5655704A

EQUIVALENT-ABSTRACTS:

A soldering ball mounting apparatus comprising: a workpiece positioning mechanism for positioning a workpiece at a predetermined position, the workpiece having an upper face formed with a number of electrodes on which soldering balls are mounted from an upside of the workpiece; a template having a number of through holes corresponding to the electrodes in a one-to-one

relationship, the template being supportable in such a manner that the through holes are positioned just above the corresponding electrodes of the workpiece; a soldering ball container provided on the template for accommodating soldering balls therein, the soldering ball container having an open bottom allowing the soldering balls to fall below the template via the through holes; and a shifting mechanism for shifting the soldering ball container along an upper surface of the template horizontally disposed.

CHOSEN-DRAWING: Dwg.1/4 Dwg.0/4

TITLE-TERMS: SOLDER BALL MOUNT DEVICE COMPRISE WORK POSITION PART POSITION WORK
ELECTRODE UP TEMPLATE THROUGH HOLE CORRESPOND ELECTRODE

DERWENT-CLASS: L03 M23 P55 U11 V04 X24

CPI-CODES: L03-F02; L03-H04E6; M23-A03;

EPI-CODES: U11-C05G2B; U11-D01A3; U11-D01A5; V04-R04A; X24-A09;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1996-089540

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